

### Product Change Notification / LIAL-07RPOQ740

# Date:

13-Dec-2022

## **Product Category:**

Ethernet PHYs

# **PCN Type:**

Manufacturing Change

## **Notification Subject:**

CCB 5135 Final Notice: Qualification of a new lead frame with more Ag area on DAP surface prep for selected KSZ8081 and KSZ8091 device families available in 32L VQFN (5x5x0.9mm) package assembled at MTAI assembly site.

## Affected CPNs:

LIAL-07RPOQ740\_Affected\_CPN\_12132022.pdf LIAL-07RPOQ740\_Affected\_CPN\_12132022.csv

## Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of a new lead frame with more Ag area on DAP surface prep for selected KSZ8081 and KSZ8091 device families available in 32L VQFN (5x5x0.9mm) package assembled at MTAI assembly site.

#### Pre and Post Change Summary:

|--|

Assembly Site	Microchip Technology Thailand (HQ)/ (MTAI)	Microchip Technology Thailand (HQ)/ MTAI				
Wire material	Au/2N	Au/2N				
Die attach material	3280	3280				
Molding compound material	G700LTD	G700LTD				
Lead frame material	A194	A194				
Lead frame DAP surface prep	Ag selective plating	Ag selective plating (Add more Ag area)				
	See Pre and Post Change Summary for comparison.					

#### Impacts to Data Sheet:None

#### Change ImpactNone

**Reason for Change:**To improve productivity by qualifying new lead frame with more Ag area on DAP surface prep.

#### Change Implementation Status: In Progress

Estimated First Ship Date: December 30, 2022 (date code: 2253)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

#### Time Table Summary:

	August 2022					>	December 2022					
Workweek	3	3	3	3	3		4	5	5	5	5	
	2	3	4	5	6		9	0	1	2	3	
Initial PCN Issue												
Date		X										
Qual Report												
Availability									Х			
Final PCN Issue												
Date									X			
Estimated												
Implementation											Х	

# Date

#### Method to Identify Change: Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**August 11, 2022: Issued initial notification. December 13, 2022: Issued final notification. Attached the Qualification Report. Updated affected parts list. Provided estimated first ship date to be on December 30, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

PCN\_LIAL-07RPOQ740\_Qual Report.pdf PCN\_LIAL-07RPOQ740\_Pre and Post Change Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. LIAL-07RPOQ740 - CCB 5135 Final Notice: Qualification of a new lead frame with more Ag area on DAP surface prep for selected KSZ8081 and KSZ8091 device families available in 32L VQFN (5x5x0.9mm) package assembled at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

KSZ8091RNBCA KSZ8081MNXCA KSZ8091MNXCA KSZ8081MNXIA KSZ8081RNBCA-TR KSZ8091RNBCA-TR KSZ8091MNXCA-TR KSZ8091MNXCA-TR KSZ8091RNBIA-TR KSZ8091RNBIA-TR KSZ8091MNXIA-TR SPNZ801174